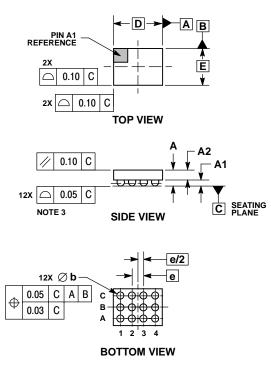
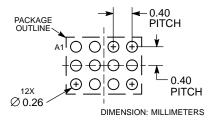




SCALE 4:1



RECOMMENDED SOLDERING FOOTPRINT



DATE 18 NOV 2015

NOTES:

NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. COPLANARITY APPLIES TO SPHERICAL <u>CROWNS OF SOLDER</u> BALLS.

CROWING OF BOLDER				
	MILLIMETERS			
DIM	MIN	MAX		
Α	0.50	0.56		
A1	0.17	0.23		
A2	0.33	0.39		
b	0.24	0.29		
D	1.62 BSC			
E	1.22 BSC			
е	0.40 BSC			

GENERIC **MARKING DIAGRAM***



XXXXX = Specific Device Code А

- = Assembly Location
- = Wafer Lot

L

Υ

- = Year
- = Work Week WW
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

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DESCRIPTION:	12 PIN FLIP-CHIP, 1.62 X 1.22, 0.4P		PAGE 1 OF 2

12 PIN FLIP-CHIP, 1.62x1.22, 0.4P CASE 499BJ ISSUE C





DOCUMENT NUMBER: 98AON48124E

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ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY B. BEYRON.	19 JAN 2010
А	CORRECTED MARKING DIAGRAM. REQ. BY M. COMBES.	07 OCT 2010
В	CORRECTED MARKING DIAGRAM TO 6 CHARACTERS. REQ. BY M. HILTON.	03 AUG 2011
С	CORRECTED MARKING DIAGRAM TO 5 CHARACTERS AND ADDED L FOR WAFER LOT. REQ. BY M. HILTON.	18 NOV 2015

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